

Sound Processor with Built-in 3-band Equalizer

BD37544FS

General Description

BD37544FS is a sound processor with built-in 3-band equalizer for car audio. The functions are stereo input selector (which can switch single and GND isolation), input-gain control, main volume, super bass, 5ch fader volume, LPF/HPF for subwoofer, and mixing input. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and can construct a high quality car audio system.

Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, super bass, mixing by using advanced switch circuit.
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces switching noise for volume of a portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer, and HPF. It is possible to control Q, Gv, fo of 3-band equalizer and fc of LPF/HPF through I²C BUS control.
- It is possible to adjust the gain of the bass, middle, and treble up to ±20dB with 1 dB step gain adjustment
- It is equipped with output terminals for Subwoofer. Moreover, the stereo signal output of the front and rear can also be chosen by the I²C BUS control.
- Built-in mixing input and mixing attenuator.
- Energy-saving design resulting in low-current consumption is achieved by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB layout.
- It is possible to control the I²C BUS by 3.3V / 5V.

Applications

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

Key Specifications

Power Supply Voltage Range: 7.0V to 9.5VCircuit Current (No Signal): 38mA (Typ)

■ Total Harmonic Distortion:

THD+N1 0.001% (Typ)
THD+N2 0.002% (Typ)

■ Maximum Input Voltage: 2.3Vrms(Typ)

Cross-talk Between Selectors: -100dB(Typ)

Volume Control Range: +15 dB to -79dB

Output Noise Voltage:

 V_{NO1} 3.8 μ Vrms(Typ) V_{NO2} 4.8 μ Vrms(Typ) Residual Output Noise Voltage: 1.8 μ Vrms(Typ) Operating Temperature Range: -40°C to +85°C

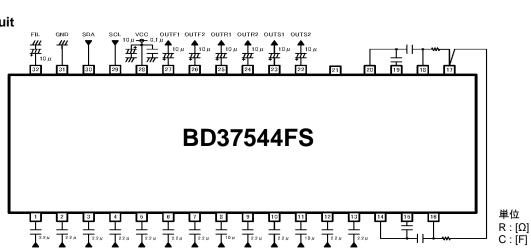
Package

W(Typ) x D(Typ) x H(Max)

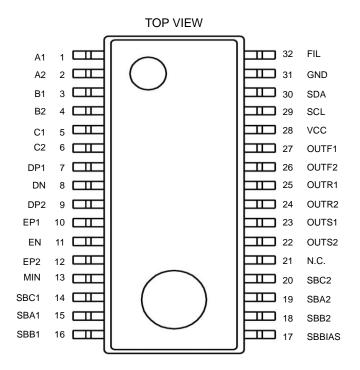


SSOP-A32 13.60 mm x 7.80mm x 2.01mm

Typical Application Circuit

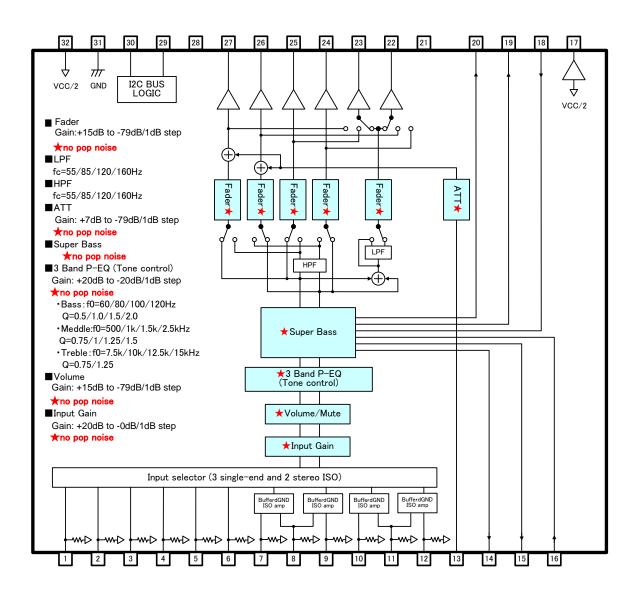


Pin Configuration



Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	17	SBBIAS	SuperBass bias terminal
2	A2	A input terminal of 2ch	18	SBB2	SuperBass setting terminal of 2ch
3	B1	B input terminal of 1ch	19	SBA2	SuperBass setting terminal of 2ch
4	B2	B input terminal of 2ch	20	SBC2	SuperBass setting terminal of 2ch
5	C1	C input terminal of 1ch	21	N.C.	No connection
6	C2	C input terminal of 2ch	22	OUTS2	Subwoofer output terminal of 2ch
7	DP1	D positive input terminal of 1ch	23	OUTS1	Subwoofer output terminal of 1ch
8	DN	D negative input terminal	24	OUTR2	Rear output terminal of 2ch
9	DP2	D positive input terminal of 2ch	25	OUTR1	Rear output terminal of 1ch
10	EP1	E positive input terminal of 1ch	26	OUTF2	Front output terminal of 2ch
11	EN	E negative input terminal	27	OUTF1	Front output terminal of 1ch
12	EP2	E positive input terminal of 2ch	28	VCC	Power supply terminal
13	MIN	Mixing input terminal	29	SCL	I ² C Communication clock terminal
14	SBC1	SuperBass setting terminal of 1ch	30	SDA	I ² C Communication data terminal
15	SBA1	SuperBass setting terminal of 1ch	31	GND	GND terminal
16	SBB1	SuperBass setting terminal of 1ch	32	FIL	VCC/2 terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	Vcc	10.0	٧
Input Voltage	V_{IN}	V _{CC} +0.3 to GND-0.3	٧
Power Dissipation	Pd	0.95 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

⁽Note 1) When mounted on the standard board (70 x 70 x 1.6 mm³), derate by 7.6mW/°C for Ta above 25°C.

Thermal resistance θja = 131.6(°C/W)

Material: A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	V _{CC}	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

Electrical Characteristics

(Unless specified, Ta=25°C, Vcc=8.5V, f=1kHz, V_{IN}=1Vrms, Rg=600 Ω , R_L=10k Ω , A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, HPF OFF, Mixing OFF, Fader 0dB)

	Deremeter		,	Limit	g = :		
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current (No Signal)	lα	-	38	48	mA	No signal
	Voltage Gain	G_V	-1.5	0	+1.5	dB	G _V =20log(V _{OUT} /V _{IN})
	Channel Balance	СВ	-1.5	0	+1.5	dB	$CB = G_{V1}\text{-}G_{V2}$
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
GENERAL	Output Noise Voltage 1 (FRONT,REAR) *	V_{NO1}	-	3.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GEN	Output Noise Voltage 2 (SUBWOOFER) *	V_{NO2}	-	4.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
	Residual Output Noise Voltage*	V_{NOR}	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Cross-talk Between Channels *	СТС	-	-100	-90	dB	$Rg = 0\Omega$ $CTC=20log(V_{OUT}/V_{IN})$ BW = IHF-A
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V _{RR} =100mVrms RR=20log(V _{CC} IN/V _{OUT})
	Input Impedance(A, B,C)	R _{IN_S}	70	100	130	kΩ	
~	Input Impedance(D, E)	R_{IN_D}	175	250	325	kΩ	
SELECTOR	Maximum Input Voltage	V_{IM}	2.1	2.3	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
UT SEL	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	Rg = 0Ω CTS= $20log(V_{OUT}/V_{IN})$ BW = IHF-A
INPUT	Common Mode Rejection Ratio*	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V _{IN} /V _{OUT}) BW = IHF-A,[*XD,E]

Electrical Characteristics - continued

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BLOCK	Parameter	Symbol	Min	Тур	Max Unit		Conditions
NIA	Minimum Input Gain	GIN_MIN	-2	0	+2	dB	Input gain 0dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
INPUT GAIN	Maximum Input Gain	G _{IN_MAX}	18	20	22	dB	Input gain 20dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
_	Gain Set Error	G _{IN_ERR}	-2	0	+2	dB	GAIN=+20dB to +1dB
MUTE	Mute Attenuation *	Gмите	-	-105	-85	dB	Mute ON GMUTE=20log(VOUT/VIN) BW = IHF-A
	Maximum Gain	G _{V_MAX}	13	15	17	dB	Volume = 15dB V_{IN} =100mVrms G_V =20log(V_{OUT}/V_{IN})
VOLUME	Maximum Attenuation *	G _{V_MIN}	-	-100	-85	dB	Volume = $-\infty$ dB G_V =20log(V V _{OUT} /V _{IN}) BW = IHF-A
9	Attenuation Set Error 1	G _{V_ERR1}	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	G _{V_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	G _{V_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
	Maximum Boost Gain	G _{B_BST}	18	20	22	dB	Gain=+20dB f=100Hz V _{IN} =100mVrms G _B =20log (V _{OUT} /V _{IN})
BASS	Maximum Cut Gain	G в_сит	-22	-20	-18	dB	Gain=-20dB f=100Hz V _{IN} =2Vrms G _B =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{B_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz
щ	Maximum Boost Gain	G _{м_вѕт}	18	20	22	dB	Gain=+20dB f=1kHz V _{IN} =100mVrms G _M =20log (V _{OUT} /V _{IN})
MIDDLE	Maximum Cut Gain	G м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V _{IN} =2Vrms G _M =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{M_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=1kHz
ш	Maximum Boost Gain	G _{T_BST}	18	20	22	dB	Gain=+20dB f=10kHz V _{IN} =100mVrms GT=20log (V _{OUT} /V _{IN})
TREBLE	Maximum Cut Gain	Gт_сит	-22	-20	-18	dB	Gain=-20dB f=10kHz V _{IN} =2Vrms GT=20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{T_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz
	Input Impedance	R _{IN_M}	19	27	35	kΩ	
SNI	Maximum Input Voltage	V _{ІМ_М}	2.0	2.2	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
MIXING	Maximum Attenuation *	Gмх_міn	-	-100	-85	dB	MIX=OFF G _{MX} =20log(V _{OUT} /V _{IN}) BW=INF-A
	Maximum Gain	G _{MX_MAX}	5	7	9	dB	ATT=+7dB G _{MX} =20log(V _{OUT} /V _{IN})

Electrical Characteristics - continued

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BLOCK	Parameter	Symbol	Limit			Unit	Conditions
BLC	Parameter	Symbol	Min	Тур	Max	Offic	Conditions
SUBWOOFER	Maximum Boost Gain	G _{F_BST}	13	15	17	dB	Fader=15dB V _{IN} =100mVrms G _F =20log(V _{OUT} /V _{IN})
	Maximum Attenuation *	G _{F_MIN}	1	-100	-90	dB	Fader = $-\infty$ dB $G_F=20\log(V_{OUT}/V_{IN})$ BW = IHF-A
BWC	Gain Set Error	G _{F_ERR}	-2	0	+2	dB	GAIN=+1dB to +15dB
/SU	Attenuation Set Error 1	G _{F_ERR1}	-2	0	+2	dB	ATT=-1dB to -15dB
FADER	Attenuation Set Error 2	G _{F_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
FAC	Attenuation Set Error 3	G _{F_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVrms
	Maximum Output Voltage	V _{OM}	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

Typical Performance Curves

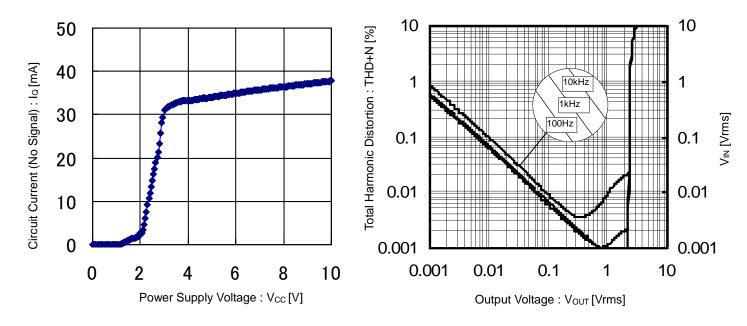


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

Figure 2. Total Harmonic Distortion vs Output Voltage

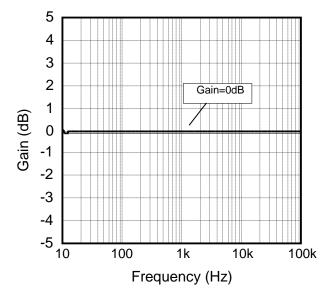


Figure 3. Gain vs Frequency

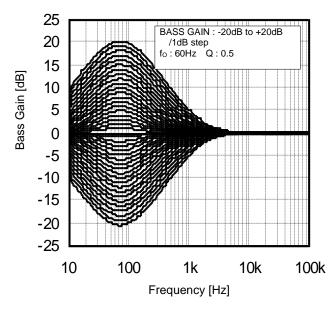


Figure 4. Bass Gain vs Frequency

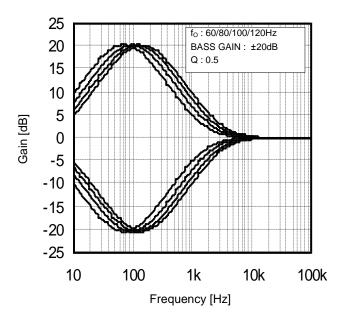


Figure 5. Bass fo vs Frequency

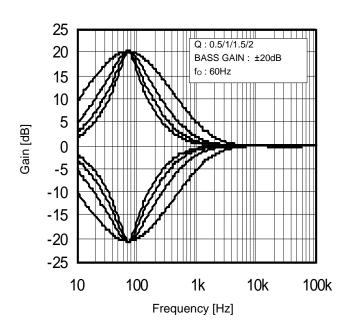


Figure 6. Bass Q vs Frequency

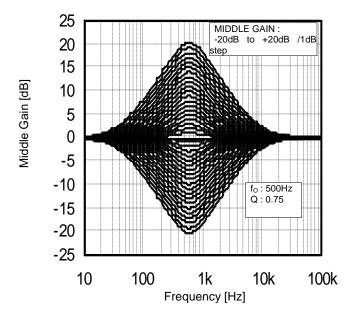


Figure 7. Middle Gain vs Frequency

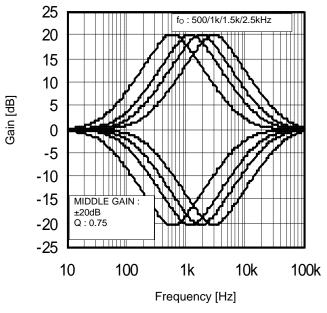


Figure 8. Middle fo vs Frequency

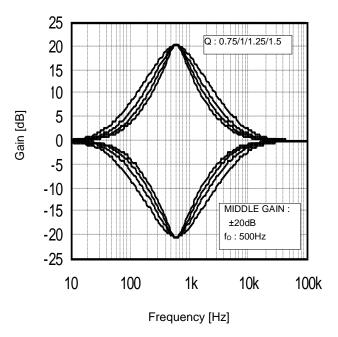


Figure 9. Middle Q vs Frequency

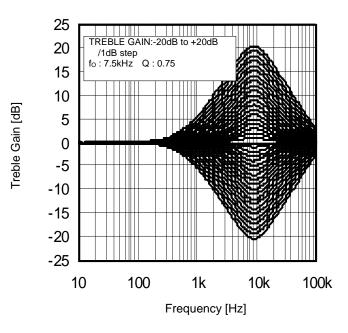


Figure 10. Treble Gain vs Frequency

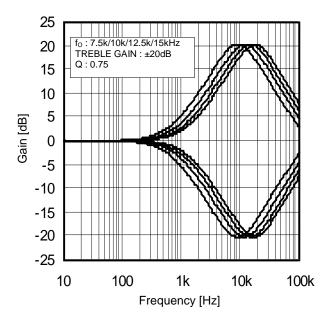


Figure 11. Treble fo vs Frequency

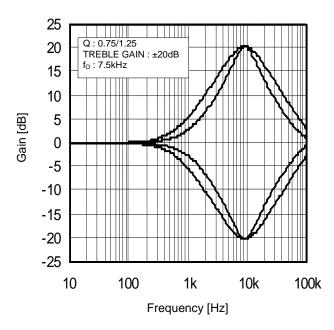


Figure 12. Treble Q vs Frequency

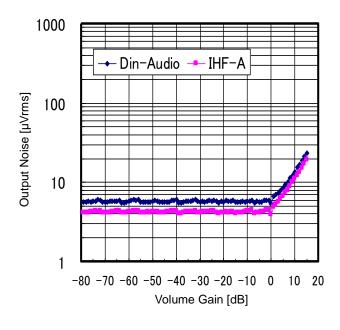


Figure 13. Output Noise vs Volume Gain

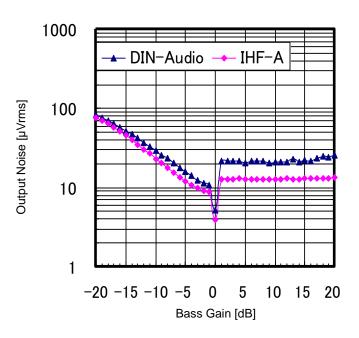


Figure 14. Output Noise vs Bass Gain

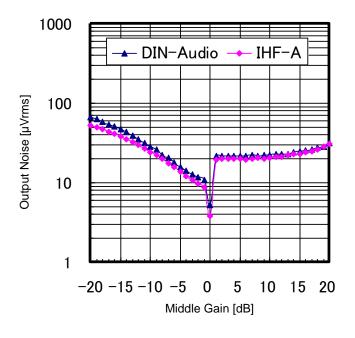


Figure 15. Output Noise vs Middle Gain

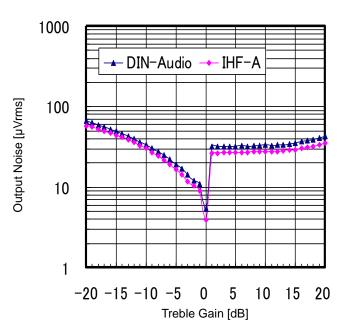


Figure 16. Output Noise vs Treble Gain

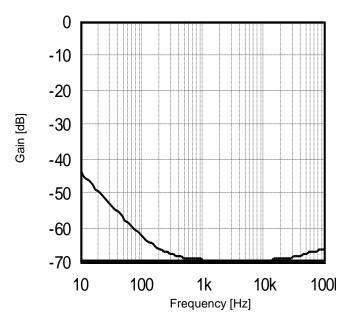


Figure 17. CMRR vs Frequency

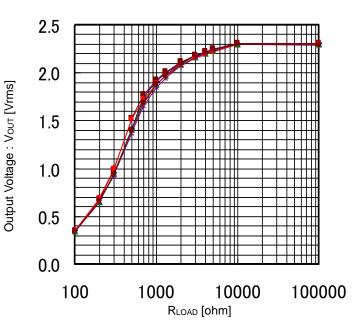


Figure 18. Output Voltage vs R_{LOAD}

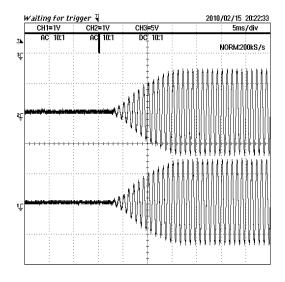


Figure 19. Advanced Switch 1

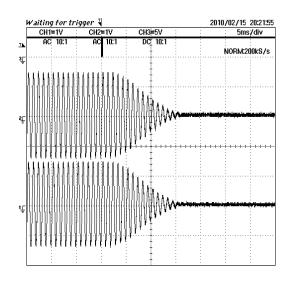


Figure 20. Advanced Switch 2

Timing Chart CONTROL SIGNAL SPECIFICATION

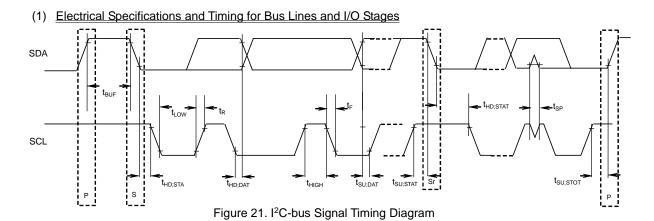


Table 1 Characteristics of the SDA and SCL bus lines for I2C-bus devices (Ta=25°C, V_{CC}=8.5V)

	•					
	Parameter	Symbol	Fast-mode	Unit		
	i didiliciti	Cymbol	Min	Max	Offic	
1	SCL clock frequency	fscL	0	400	kHz	
2	Bus free time between a STOP and START condition	t _{BUF}	1.3	-	μS	
3	Hold time (repeated) START condition. After this period, the first clock	t _{HD;STA}	0.6			
3	pulse is generated		0.6	-	μS	
4	LOW period of the SCL clock	tLOW	1.3	-	μS	
5	HIGH period of the SCL clock	thigh	0.6	-	μS	
6	Set-up time for a repeated START condition	t _{SU;STA}	0.6	-	μS	
7	Data hold time:	thd;dat	0.06 (Note)	-	μS	
8	Data set-up time	tsu;dat	120	-	ns	
9	Set-up time for STOP condition	t _{SU;STO}	0.6	-	μS	

All values refer to VIH Min and VIL Max Levels (see Table 2).

(Note) A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

For $7(t_{\text{HD;DAT}})$, $8(t_{\text{SU;DAT}})$, make the setup in which the margin is full.

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Parameter	Cumbal	Fast-mode	Unit	
	Falameter	Symbol	Min	Max	Offic
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	ViH	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	t _{SP}	0	50	ns
13	LOW level output voltage: at 3mA sink current	V _{OL1}	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	lı	-10	+10	μΑ

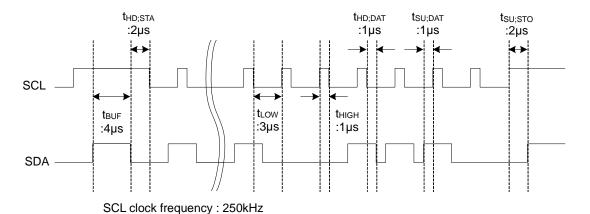


Figure 22. A Command Timing Example in the I²C Data Transmission

(2) <u>I²C BUS FORMAT</u>

	MSB LSB		MSB L	SB	MSB L	_SB						
S	Slave Address	Α	Select Address	Α	Data		Α	Р				
1bit	8bit	1bit	8bit	1bit	8bit	1	bit	1bit				
	S	= Sta	art condition (Recogi	nition of	start bit)							
	Slave Address	= Re	= Recognition of slave address. The first 7 bits correspond to the slave address									
		The least significant bit is "L" which corresponds to write mode.										
	Α	= ACKNOWLEDGE bit (Recognition of acknowledgement)										
	Select Address	= Select address corresponding to volume, bass or treble.										
	Data	= Data on every volume and tone.										
	P	= Sto	on condition (Recogn	nition of	ston hit)							

(3) I²C BUS Interface Protocol

(a) Basic Format

1-7									
S	Slave Address	Α	Selec	Α	Dat	Data		Р	
	MSB LS	B	MSB	LSB	N	1SB	LSE	3	

(b) Automatic Increment (Select Address increases (+1) according to the number of data.)

S	Slave Address	Α	Select Address	Α	Data1	Α	Data2	Α		DataN	Α	Р
(Exar	-	SB	MSB LS	В	MSB LS	В	MSB	LS	В	MSB	LS	В

- Data1 shall be set as data of address specified by Select Address.
 Data2 shall be set as data of address specified by Select Address +1.
- ③ DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration Unavailable for Transmission (In this case, only Select Address1 is set.)

(-)	garane contraction to the contraction (in the contraction)										
SS	Slave Address	A Select	Address1	A Dat	a A	Select	Address 2	Α	Data	a A	Р
MS	B LSE	3 MSB	LSB	MSB	LSB	MSB	LSB	N	ISB	LSB	
	(Note) If any data is transmitted as Select Address 2 next to data, it is recognized										
	as data, not as Select Address 2.										

(4) Slave Address

MSB							LSB	
A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

(5) Select Address & Data

Items	Select Address	MSB			Da	ata			LSB	
Items	(hex)	D7	D6	D5	D4	D3	D2	D1	D0	
Initial setup 1	01	Advanced switch ON/OFF	0	Input Gai	witch time of n/Volume /Super Bass ting	0	1		switch time /lute	
Initial setup 2	02	LPF Phase	0		er Output lect	0	Su	bwoofer LPI	= f _C	
Initial setup 3	03	Front HPF Pass	Rear HPF Pass	Fro	nt / Rear HP	F f _C	0	1	0	
Input Selector	05	Full-diff Type	0	0 Input selector						
Input gain	06	Mute ON/OFF	0							
Volume gain	20			\	/olume Gain	/ Attenuatio	n			
Fader 1ch Front	28				Fader Gain	/ Attenuation	1			
Fader 2ch Front	29	Fader Gain / Attenuation								
Fader 1ch Rear	2A	Fader Gain / Attenuation								
Fader 2ch Rear	2B				Fader Gain					
Fader Subwoofer	2C				Fader Gain	/ Attenuation	1			
Mixing	30				Mixing Gain	/ Attenuation	า			
Bass setup	41	0	0	Bas	s f ₀	0	0	Bas	ss Q	
Middle setup	44	0	0	Midd	lle fo	0	0	Midd	dle Q	
Treble setup	47	0	0	Treb	ole fo	0	0	0	Treble Q	
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain			
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain					
Treble gain	57	Treble Boost/ Cut	0	0						
Super Bass Gain	75	0	0	0 0 Super Bass Gain						
System Reset	FE	1	0	0	0	0	0	0	1	

Advanced switch

Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

- 3. Advanced switch is not used for the function of input selector and subwoofer output select, etc. Therefore, please apply mute on the side when changing these settings.
- 4. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF for waiting advanced-mute time.

Select address 01 (hex)

Time	MSB	MSB Advanced switch time of Mute LS								
TITLE	D7	D6	D6 D5 D4 D3 D2 D1							
0.6msec	Advanaad		Advanced switch time of Input gain/Volume Tone/Fader/Super Bass/Mixing				0	0		
1.0msec	Advanced Switch	0			0	4	0	1		
1.4msec						1	1	0		
3.2msec	ON/OFF						1	1		

Time	Advanced switch time of Input MSB gain/Volume/Tone/Fader/ LSE										
Time		Super Bass/Mixing									
	D7	D6	D5	D4	D3	D2	D1	D0			
4.7 msec	Advanced Switch ON/OFF	A al. (2 2 2 2 2 d		0	0						
7.1 msec		vitch 0	0	1	0	1	Advanced switch				
11.2 msec			1	0			Time	of Mute			
14.4 msec			1	1							

Mode	MSB	B Advanced switch ON/OFF							
IVIOGE	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	Advanced switch time of Input gain/Volume		0	1		ed switch	
ON	1		Tone/Fader/Super Bass/Mixing			,	Time o	of Mute	

Select address 02(hex)

DOIGOT GGGGGGG								
fo	MSB Subwoofer LPF fc							LSB
TC TC	D7	D6	D5	D4	D3	D2	D1	D0
OFF						0	0	0
55Hz					0	0	0	1
85Hz	LPF	_	O Subwoofer Output Select	0		1	0	
120Hz	Phase	U		lect	U	0	1	1
160Hz						1	0	0
Prohibition						Other setting		

Mode	MSB	MSB Subwoofer Output Select LSI								
Mode	D7	D6	D5	D4	D3	D2	D1	D0		
LPF			0	0						
Front	LPF Phase	•	0	1			- ,			
Rear			1	0	Ü	Subwoofer LPF fc				
Prohibition			1	1						

Phase	MSB				LSB			
	D7	D6	D5	D4	D3	D2	D1	D0
0°	0	0	Subwoofer output		0	Subwoofer LPF fc		E fo
180°	1	U	sel	lect	U	Subwooter LPF to		1 10

Select address 03(hex)

COICOL GGGIOOG CO(ITOX	•)								
Mode	MSB Front/Rear HPF fc								
iviode	D7	D6	D5	D4	D3	D2	D1	D0	
55Hz			0	0	0				
85Hz	Front	Rear HPF Pass	0	0	1	0	1	0	
120Hz	HPF		1	1	0				
160Hz	Pass		0	1	0				
Prohibition			(Other setting	9				

Mode	MSB				LSB			
Mode	D7	D6	D5	D4	D3	D2	D1	D0
pass	Front	0	Г		Γ.	0	4	0
NOT pass	HPF Pass	1	FIC	ont/Rear HP	r ic	U	1	0

Mode	MSB			Front HPF					
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
pass	0	Rear		nt/Door UD	⊏ 4-	0	4	0	
NOT pass	1	HPF Pass	FIC	ont/Rear HP	r ic		l I	U	

Select address 05(hex)

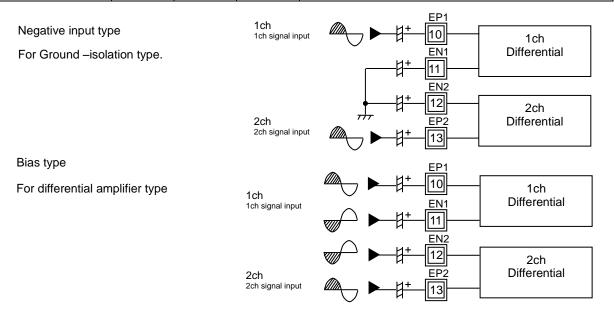
Delect addi	1	<i>3</i> 7,	NACD		1		-14			1.00
Mode			MSB		In	put S	electe	or		LSB
Mode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0
Α	A1	A2				0	0	0	0	0
В	B1	B2				0	0	0	0	1
С	C1	C2	Full- diff bias			0	0	0	1	0
D single	DP1	DP2				0	0	0	1	1
E single	EP1	EP2				0	0	1	0	0
A diff	A1	B1		0	0	0	1	1	1	1
C diff	B2	C2	type select			1	0	0	0	0
D diff	DP1	DP2	361661			0	0	1	1	0
E diff	EP1	EP2				0	0	1	1	1
In	Input SHORT					0	1	0	0	1
Prohibition					Other setting					

Input SHORT: The input impedance of each input terminal is lowered from $100k\Omega(Typ)$ to $6~k\Omega(Typ)$.

(For quick charge of coupling capacitor)

Select address 05(hex)

Mode	MSB	F	-ull-di	ff Bias	Туре	Selec	t	LSB	
iviode	D7	D6	D5	D4	D3	D2	D1	D0	
Negative Input	0	0	0		I.	anut Calaata	r		
Bias	1	0	0	Input Selector					



Select address 06 (hex)

Gain	MSB	<u> </u>		Inpu	ıt Gair	1		LSB	
Gairi	D7	D6	D5	D4	D3	D2	D1	D0	
0dB				0	0	0	0	0	
1dB				0	0	0	0	1	
2dB				0	0	0	1	0	
3dB				0	0	0	1	1	
4dB				0	0	1	0	0	
5dB				0	0	1	0	1	
6dB				0	0	1	1	0	
7dB				0	0	1	1	1	
8dB				0	1	0	0	0	
9dB		0		-	0	1	0	0	1
10dB				0	1	0	1	0	
11dB	Mute			0	1	0	1	1	
12dB	ON/OFF		0	0	1	1	0	0	
13dB				0	1	1	0	1	
14dB				0	1	1	1	0	
15dB				0	1	1	1	1	
16dB				1	0	0	0	0	
17dB				1	0	0	0	1	
18dB				1	0	0	1	0	
19dB				1	0	0	1	1	
20dB				1	0	1	0	0	
				1	1	0	1	1	
Prohibition				:	:	:	:	:	
				1	1	1	1	1	

Select address 06 (hex)

001001 000000 00 (110	7.9								
Mode	MSB	Mute ON/OFF LS							
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	0			Input Cain			
ON	1	0	0			Input Gain			

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	I, Fad	er Gai	n / Att	enuati	on	LSB
Gaill & Al I	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 30(hex)

Gain & ATT	MSB	ľ	dixing	Gain	/ Atter	nuation	า	LSB
Gairi & Ai i	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	1	0	0	0
7dB	0	1	1	1	1	0	0	1
6dB	0	1	1	1	1	0	1	0
5dB	0	1	1	1	1	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
MIX OFF	1	1	1	1	1	1	1	1

(Note) See the precaution on P30 together, too.

:	Initial	condition

Select address 41(hex)

Q factor	MSB	}	В		LSB			
Qiacioi	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	_	0	Dogg f	20 f -		0	0	1
1.5	0		Bass f ₀		0	U	1	0
2.0							1	1

fo	MSB				LSB			
IO	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz]	0	0	1	_	0	Ва	ass actor
100Hz	7 0	0	1	0	0	U	Q fa	actor
120Hz	7		1	1				

Select address 44(hex)

	/							
Q factor	MSB		Middle Q factor					LSB
Qiacioi	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	_		Mida	dle fo		0	0	1
1.25	U	0	ivilde	ale io	0	U	1	0
1.5							1	1

•	MSB			Middl		LSB		
10	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz	_	0	0	1	_		Mid	ddle
1.5kHz] 0	U	1	0] 0	0	Q fa	actor
2.5kHz			1	1				

Select address 47 (hex)

Ocicol addices +1 (iic)	^)							
Q factor	MSB	}	Tı	LSB				
QTactor	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Trob	olo fo	0	0	0	0
1.25] 0	U	l liet	ole fo	U	U	U	1

fo	MSB	•			LSB			
TO	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz			0	0				
10kHz	0	0	0	1	0	0	_	Treble Q factor
12.5kHz	U	U	1	0			0	Q factor
15kHz			1	1				

Select address 51, 54, 57 (hex)

Gain	MSB		Bass/l	\cap	LSB			
Gaiii	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB			0	0	1	0	0	0
9dB				0	1	0	0	1
10dB	Bass/			0	1	0	1	0
11dB	Middle/			0	1	0	1	1
12dB	Treble	0		0	1	1	0	0
13dB	Boost			0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
1.101110111				1	1	1	1	0
				1	1	1	1	1

Mode	MSB	Ва	ss/Mid	ddle/T	reble l	3oost/	Cut	LSB	
Mode	D7	D6	D6 D5 D4 D3 D2 D1						
Boost	0	0	0	Bass/Middle/Treble Gain					
Cut	1	U	0	Bass/Middle/Treble Gain					

Select address 75 (hex)

Gain	MSB		Sı	ıper B	LSB			
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB]	_	_	0	1	0	1	1
12dB	0	0	0	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:		:	:	:
				1	1	1	1	1

(Note) About Super Bass, the above Gain is for in indication purposes. Actual Gain (=20log (Vout/VIN)) is different. Refer to P31 to P34 for the details.

· Initia	I condition
. II II ua	i conunition

(6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn ON mute until this initial data is sent.

Daramatar	Cumbal	•	Limit		Linit	Conditions
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Rise Time of VCC	trise	33	-	-	µsec	V _{CC} rise time from 0V to 5V
VCC Voltage of Release Power ON Reset	V _{POR}	-	4.1	-	V	

Application Information

1.

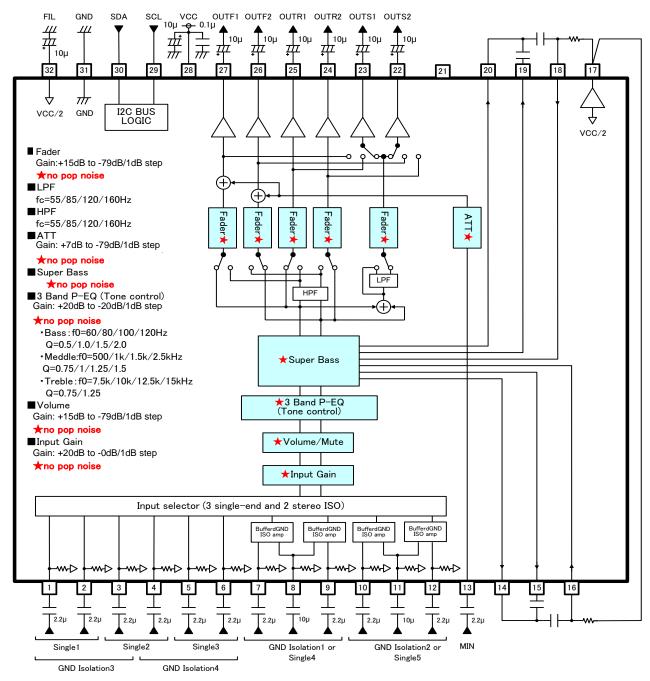
Function and Specific		ontions								
Function	Specifications Specifications									
	Stereo input Single End/Differential									
	· Single-End/Differential									
	(Possible to set the number of single-end/ differential as follows)									
Input selector	Single-End Mode 1 0	Differential 4								
	Mode 2 1	3								
	Mode 3 3 Mode 4 4	2								
	Mode 5 5	0								
	Table.1 Combination	of input selector								
Input gain	· +20dB to 0dB (1dB step)									
	Possible to use "Advanced switch" for prev	ention of switching noise.								
Mute	· Possible to use "Advanced switch" for prev	ention of switching noise.								
Volume	· +15dB to -79dB (1dB step), -∞dB									
volumo	Possible to use "Advanced switch" for prev	ention of switching noise.								
	· +20dB to -20dB (1dB step)									
Bass	· Q=0.5, 1, 1.5, 2									
Dass	· f ₀ =60, 80, 100, 120Hz									
	· Possible to use "Advanced switch" for prevention of switching noise.									
	· +20dB to -20dB (1dB step)									
Middle	· Q=0.75, 1, 1.25, 1.5									
Middle	· fo=500, 1k, 1.5k 2.5kHz									
	· Possible to use "Advanced switch" for prev	ention of switching noise.								
	· +20dB to -20dB (1dB step)									
T	· Q=0.75, 1.25									
Treble	· fo=7.5k, 10k, 12.5k, 15kHz									
	· Possible to use "Advanced switch" for prev	ention of switching noise.								
	· +15dB to -79dB(1dB step), -∞dB									
Fader	Possible to use "Advanced switch" for prev	ention of switching noise.								
	· fc=55/85/120/160Hz, pass	-								
LPF	• Phase shift (0°/180°)									
HPF	· fc=55/85/120/160Hz, pass									
· Monaural input										
Mixing	· +7dBdB to -79dB (1dB step), -∞dB									
J	Possible to use "Advanced switch" for prevention of switching noise.									
	· +20dB to 0dB (1dB step)	<u> </u>								
Super Bass	1,	ention of switching noise								
	Possible to use "Advanced switch" for prevention of switching noise.									

2. Volume / Fader Volume / Mixing ATT Attenuation Data

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6	1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9 -10	1	0	0	0	1	0	<u>0</u>	1 0	-57 -58	1	0	1	1	1	0	1	0
-10	1	0	0	0	1	0	1	1	-56 -59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-∞	1	1	1	1	1	1	1	1

Adjustable range of mixing ATT is +7dB to $-\infty dB$.

3. Application Circuit



*About single input 1 to 3 it is possible to change from single input to GND Isolation input 3,4.

*About GND Isolation1 and GND Isolation2, it is possible to change from differential input to single input 4 to 5.

Figure 23. BD37544FS

Unit $R: [\Omega]$ C:[F]

Notes on wiring

- ①Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- ②GND lines should be one-point connected.
 ③Wiring pattern of Digital should be away from that of Analog unit and cross-talk should not be acceptable.
- 4SCL and SDA lines of I²C BUS should not be parallel if possible.
 - The lines should be shielded, if they are adjacent to each other.
- Sanalog input lines should not be parallel if possible. The lines should be shielded, if they are adjacent.
- ⑥Please short Pins 15-16, and Pins 18-19 if the Super Bass is not used.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy elements. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

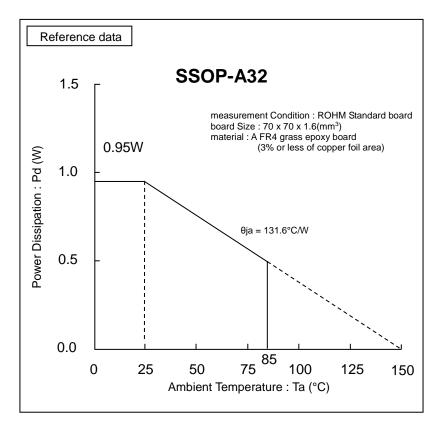


Figure 24. Temperature Derating Curve (Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

<u>O Equivale</u>	ent Circuits	<u> </u>		
Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25	VCC Δ 100KΩ	A terminal for signal input. The input impedance is 100kΩ(Typ).
7 8 9 10 11 12	DP1 DN DP2 EP1 EN EP2	4.25	VCC Δ ΨΘ Φ Φ Φ Φ Φ Φ Φ Φ Φ Φ Φ Φ Φ	Input terminal available to ingle/Differential mode. The input impedance is $250 k\Omega(\text{Typ})$.
16 18	SBB1 SBB2	-	VCC VO	An input terminal for Super Bass
15 17 19 22 23 24 25 26 27	SBA1 SBBIAS SBA2 OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND GND	A terminal for Super Bass and fader, Subwoofer output.
14 20	SBC1 SBC2	4.25	VCC Θ 3KΩ Θ Θ Θ	An output terminal for Super Bass.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

I/O Equivalent Circuits - continued

O Equivale Terminal	Terminal	Terminal		
No.	Name	Voltage	Equivalent Circuit	Terminal Description
28	VCC	8.5		Power supply terminal.
29	SCL	-	VCC O 1.65V	A terminal for clock input of I ² C BUS communication.
30	SDA	-	VCC O O J J J 1.65	A terminal for data input of I ² C BUS communication.
31	GND	0		Ground terminal.
32	FIL	4.25	VCC Solve So	1/2 VCC terminal. Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.
13	MIN	4.25	VCC Δ A B 27KΩ	A terminal for signal input. The input impedance is 27kΩ(typ).

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes - continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

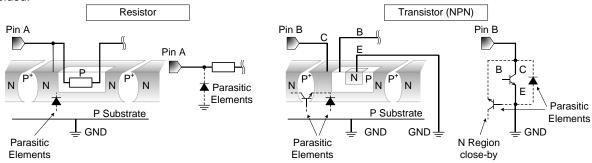
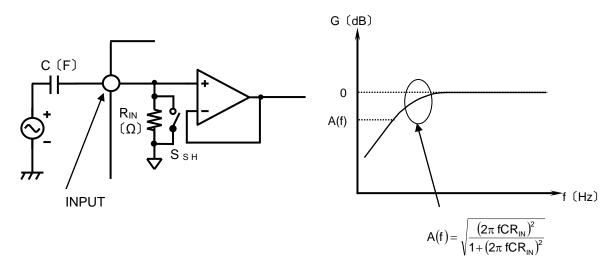


Figure 25. Example of monolithic IC structure

13. About Signal Input

(a) About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance $R_{IN}(\Omega)$ at the input signal terminal of the IC. The first HPF characteristic of RC is composed.



(b) About the Input Selector SHORT

SHORT mode is the command which makes switch S_{SH} =ON of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

Operational Notes - continued

14. About MIX

(1) About Specification of Fader -∞ at MIX ON.

Mix_signal is added to Main_signal after Fader_Gain(+15dB to -79dB) like the figure. When Fader is set at -∞, the signal after a MIX signal is added is done with MUTE because the -∞ circuit of Fader is in the step after the addition circuit

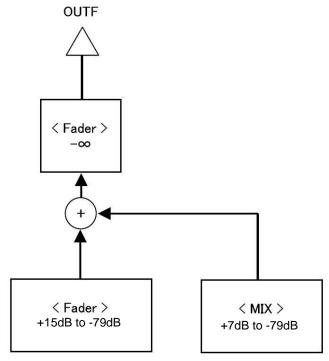
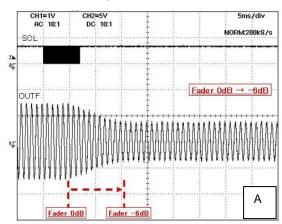


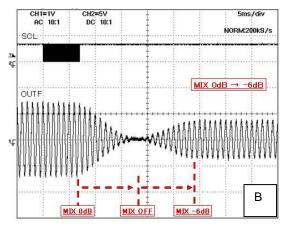
Figure 26. About Front Fader and MIX

(2) About Advanced Switching of MIX Gain/ATT

When advanced switching of MIX_Gain/ATT works, MIX goes a switching movement that it passes through the state of MIX_OFF like in B figure below (from current setting of MIX_Gain/ATT to MIX_OFF to a target setting of MIX_Gain/ATT).



Fader_Gain/ATT 0dB to -6dB advanced switching



MIX_Gain/ATT 0dB to -6dB advanced switching

Figure 27. Advanced Switching Movement when MIX_Gain/ATT is Changed

Operational Notes - continued

15. About Super Bass Circuit

The (the following Super Bass) which strengthens a low band like the graph below a can be realized by composing an external circuit with the pin 14 to 20 as shown in Figure 28.

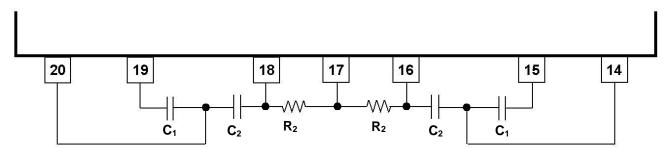


Figure 28. Super Bass circuit

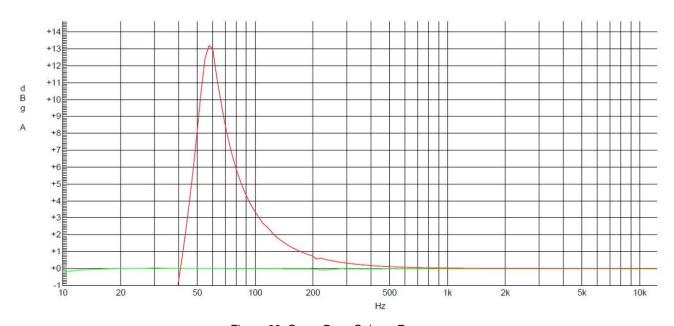


Figure 29. Super Bass Gain vs Frequency

(a) <u>Gain Step Width becomes a Logarithm</u> When a setup of Gain is made 0,1,2,3,5,7,11,20dB, it becomes the following (bottom right) character. $(C_1=0.047\mu\text{F},\,C_2=0.1\mu\text{F},\,R_1=3k\Omega,\,R_2=560k\Omega)$

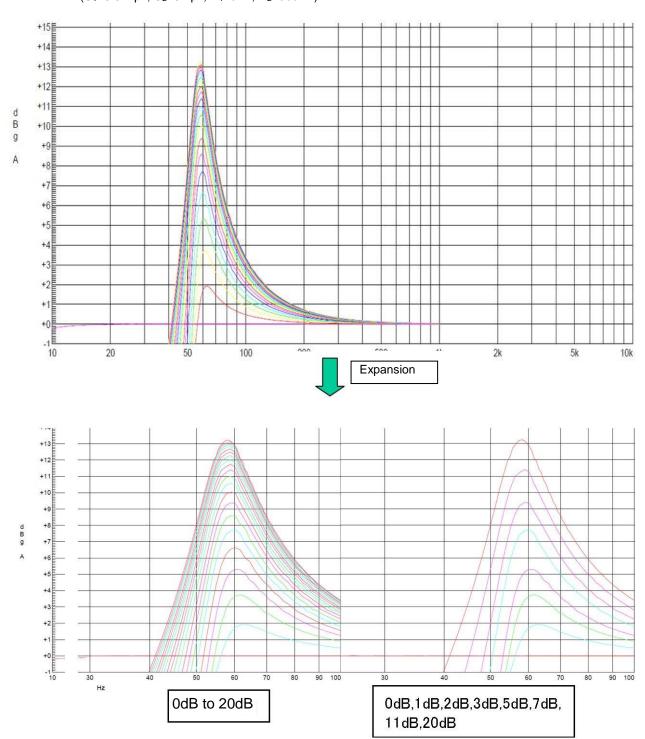
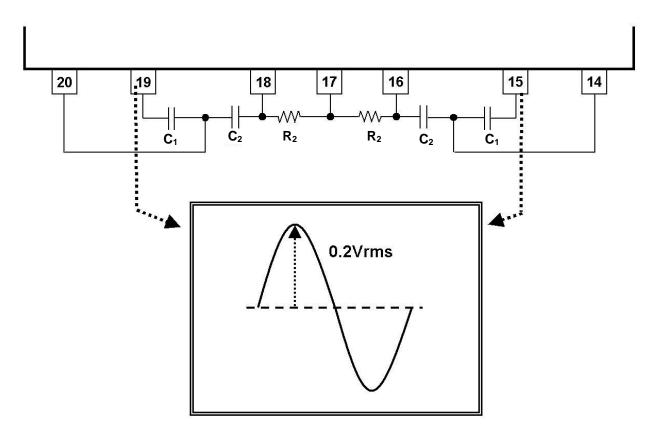


Figure 30. About Gain step of Super Bass

(b) You must take level diagram into consideration so that output may not do a clip

 $\frac{\text{Example }(C_1 = 0.047 \mu \text{F, } C_2 = 0.1 \mu \text{F, } R_2 = 560 \text{kohm, } V_{\text{CC}} = 8.5 \text{V})}{\text{To prevent output clipping due to amplification when Super Bass is used, adjust the level diagram with }}$ volume until the Tone output level becomes less than 0.2Vrms.



Please adjust so that the maximum level of the Tone output becomes less than 0.2Vrms. (at Vcc=8.5V)

Figure 31. Super Bass Level Diagram

(c) About fo and Gain of Super Bass

 f_0 and Gain of Super Bass deviates due to the deviation of the value of C_1 , C_2 , R_2 (Components with the outside),

R₁ (the resistance built in IC).

Example: Super Bass Gain – frequency characteristic at Dispersion condition of C_1 , C_2 , $R_2 \pm 5\%$, $R_1 \pm 30\%$ ($C_1 = 0.047 \mu F$, $C_2 = 0.1 \mu F$, $R_1 = 3 kohm$, $R_2 = 560 kohm$, Super Bass Gain=20dB)

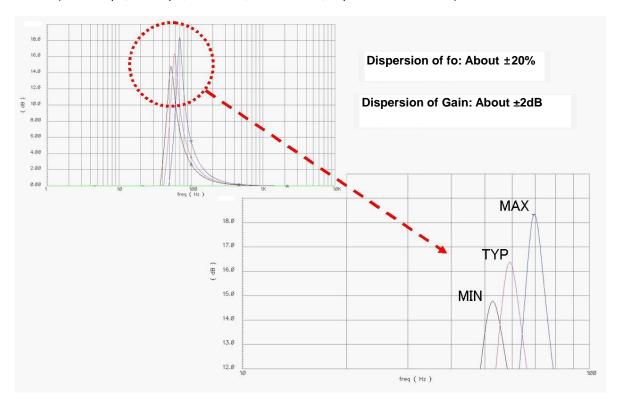
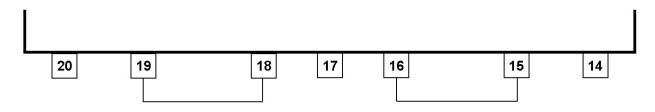


Figure 32. Dispersion of fo and Gain of Super Bass

(d) How to Deal with Pins of Super Bass when not used

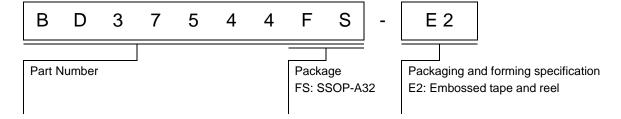
Short Pins 15 to 16, Pins 18 to 19 as shown in Figure 33 when the Super Bass function is not used.



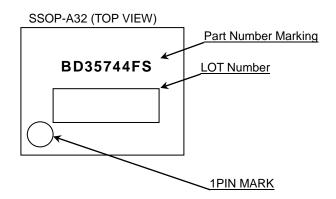
Short Pin 15 to 16, Pin 18 to 19

Figure 33. How to Deal with Pins of Super Bass when not used

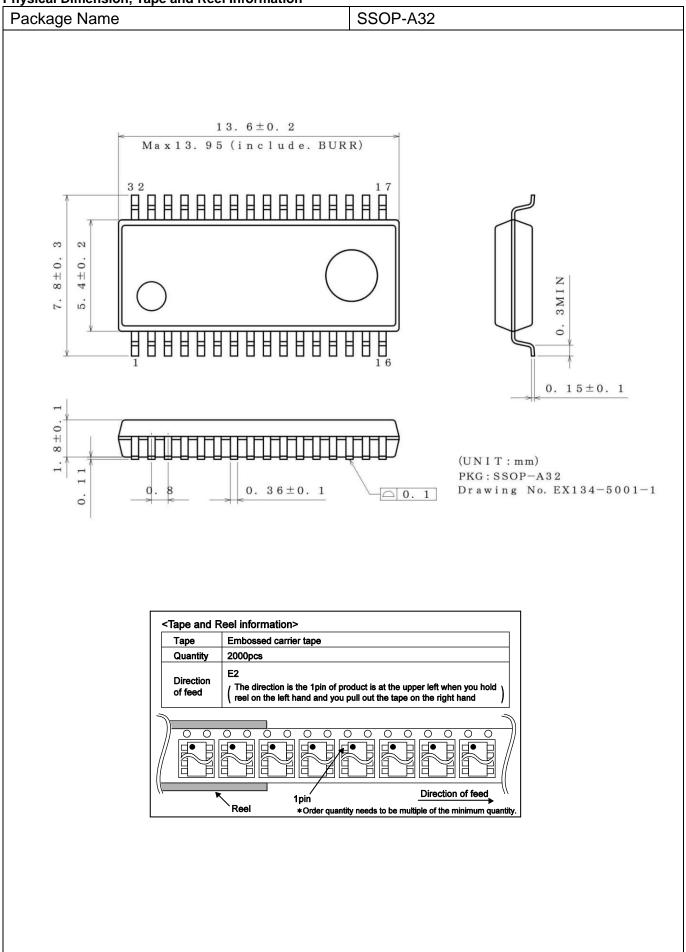
Ordering Information



Marking Diagram



Physical Dimension, Tape and Reel Information



Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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